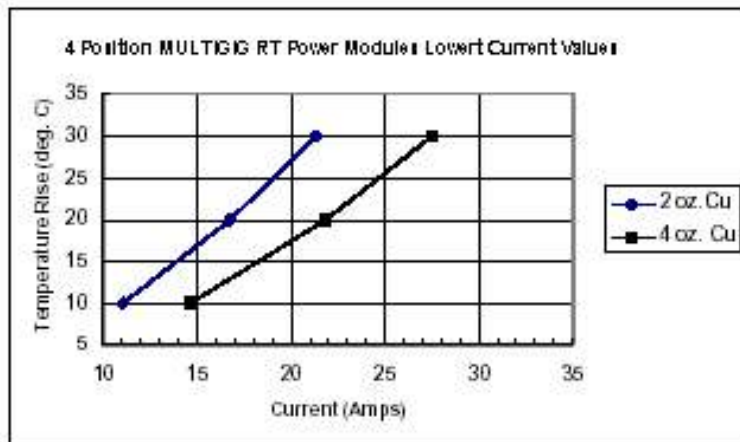
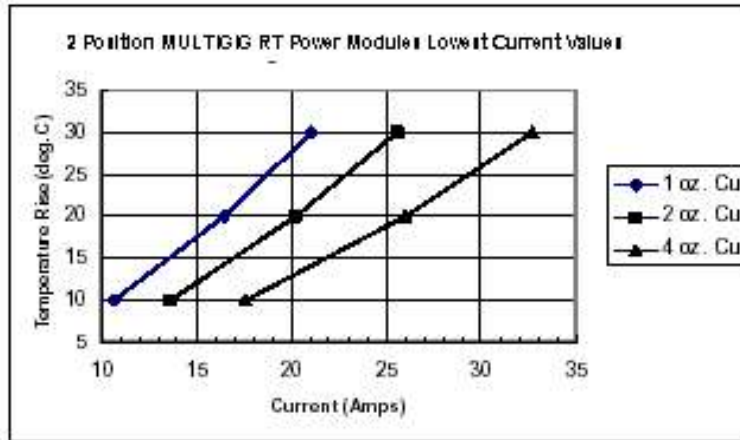


Current Rating of MULTIGIG RT* Power Modules

1. INTRODUCTION

Testing was performed to determine the current rating for 2 and 4 position MULTIGIG RT* Power Module connectors when used on printed circuit boards with 1, 2 or 4 ounce thick copper planes. Current rating is no higher than the lowest current results recorded throughout the testing at the maximum acceptable temperature rise for the application. For each connector position size, printed circuit board copper thickness and temperature rise case, the lowest currents recorded are shown in the following graphs. Contact Tyco Electronics Engineering for recommendations on your application.



2. TEST DETAILS

With all circuits energized, current, temperature rise and resistance measurements were obtained initially and after environmental exposure. Motherboard trace width is 20.3 mm, similar to daughtercard pitch. Anti-pads are 1.5 mm. Test report CTLB025258-015 is on file at the Engineering Assurance Product Test Laboratory. Reference Tyco Electronics drawing 60-474139 which defines the 60-474132-1 and 60-474133-1 test boards used for this Temperature Rise testing.